EXHIBIT & SPONSORSHIP APPLICATION

We hereby apply for exhibit space and/or sponsorship at the 65th Electronic Materials Conference (EMC) being held at the University of California, Santa Barbara, June 28-July 30, 2023 and agree to make payment at the rates listed on this application.

COMPANY INFORMATION (as it should be published)

Company Name			
Room/Dept./Mail Stop		P.O. Box	
Street			
City		State	
Zip/Postal Code		Country	
Company Tel.			
Company E-mail		Web Address	
EXHIBITOR PR	ROFILE	LISTING Desc	ription (50-word limit)
KEY PRODUCT	「S (up to 10	O - separate with semi-c	olons)
CONTACT INF	ORMAT	ION	
CONTACT INT	UIIIMAI	ION	
Exhibit Contact			
Tel.	Ext.	E-mail	
AGREEMENT			
The undersigned hereby res EMC 2023 .	serves exhibi	t space for use by the co	ompany listed above during
Applicant's Authorized Signatur	e		Date

By participating as an Exhibitor and/or Sponsor at EMC 2023 you agree to adhere to the MRS Code of Conduct.

EXHIBIT & SPONSORSHIP OPTIONS

(Select all that apply)

EXHIBIT PRICING □ Standard Booth (EMC Only)\$1,500 ☐ Standard Booth (EMC & DRC).....\$2,600 LITERATURE DISPLAY ☐ Literature Display (EMC Only)\$500 Literature Display (EMC & DRC).....\$750 **CONFERENCE SPONSORSHIP OPPORTUNITIES** ☐ Website Banner Ad\$1.250 Pre-conference Email Blast.....\$750 Program Book Ad\$500 **REGISTRATION AREA SPONSORSHIPS** ☐ Badge Lanyards*.....\$1,500 ☐ Conference Pens*.....\$1,000 Registration Bowl Give-away*.....\$500 **EVENT SPONSORSHIPS** □ Welcome Poster Reception\$3,000 Conference Banguet\$5,000 Refreshment Break (3 available).....\$1,500 Sponsorship opportunities do not include registration badges unless noted. *Materials must be provided by sponsor. **TOTAL ENCLOSED** PAYMENT DETAILS Check (payable to Materials Research Society) in the amount of Credit Card Check here to have invoice sent with credit card payment information. Wire Transfer

RETURN TO:

Jennifer Ibe

MRS Exhibit & Sponsorship Sales 98 East Chicago Avenue, Suite 201 Westmont, Illinois 60559 MRS@heiexpo.com Phone: 630.929.7964

Fax: 630.434.1216

Application must be received by April 28, 2023 for recognition in the Conference Program.

Contact MRS@heiexpo.com for ACH/Wire Payment details.

Cancellations received after April 28, 2023 no refunds will be made.